

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	chip adj package and soft and hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:52
L2	3	Chen near Huei-Jen .inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:52
L3	3	package and soft and hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:52
L4	4	substrate and soft and hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:52
L5	918	substrate and soft and hard and pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:53
L6	127	substrate and soft and hard same pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 11:53
L7	78	substrate and soft and hard same pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 12:02
L8	1	multi near layer near PCB and soft and hard near composite	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 12:05
L9	1	PCB and soft and hard near composite	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 12:05
L10	1	soft adj hard near composite and board	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 12:05

L11	13	soft adj hard near composite	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 13:44
L12	689	chip adj package near substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:04
L13	0	chip adj package near substrate and hard and soft near composite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 13:47
L14	6	chip adj package near substrate and hard and soft	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 13:50
L15	107	chip adj package near substrate and composite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 13:50
L16	32	("3953566"   "4482516"   "4591659"   "4654248"   "4705762"   "4890194"   "4943844"   "4985296"   "5103293"   "5339217"   "5455385"   "5506756"   "5532513"   "5545473"   "5572405"). PN. OR ("5900312").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/23 13:56
L17	0	chip adj package and hard near soft near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:07
L18	0	chip and hard near soft near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:08
L19	1	hard near soft near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:13
L20	0	hard near soft near composition and pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:14

L21	241	hard near soft near composition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:14
L22	3	soft adj circuit near board and hard adj circuit near board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:17
L23	3	soft adj circuit near board and hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:18
L24	0	soft adj hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:18
L25	4	soft same hard near pcb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 14:18
L26	32	("3953566"   "4482516"   "4591659"   "4654248"   "4705762"   "4890194"   "4943844"   "4985296"   "5103293"   "5339217"   "5455385"   "5506756"   "5532513"   "5545473"   "5572405"). PN. OR ("5900312").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/23 14:19
L27	18	("3912849"   "4810563"   "4922378"   "5055967"   "5220487").PN. OR ("5339217").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/23 14:36
L28	17	("5900312").URPN.	USPAT	OR	ON	2006/01/23 14:38